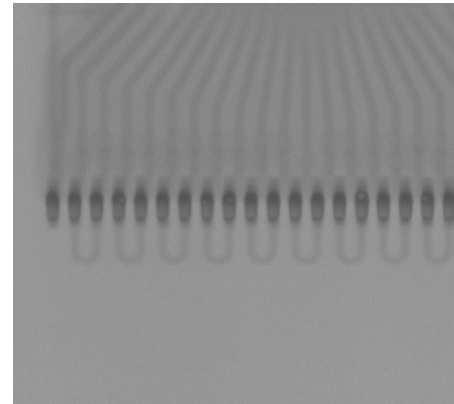
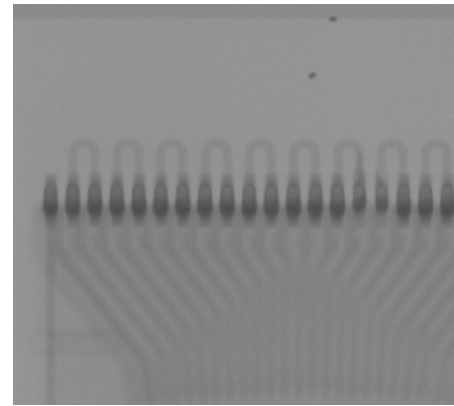
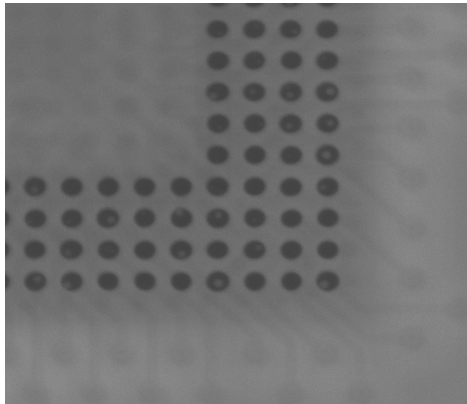
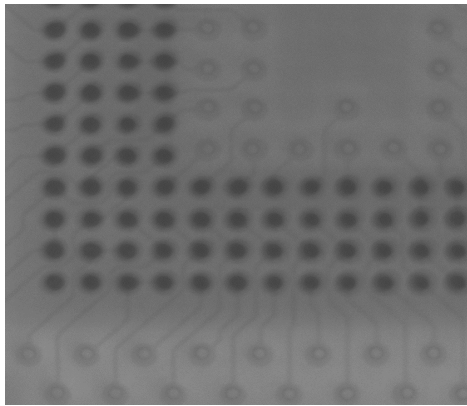
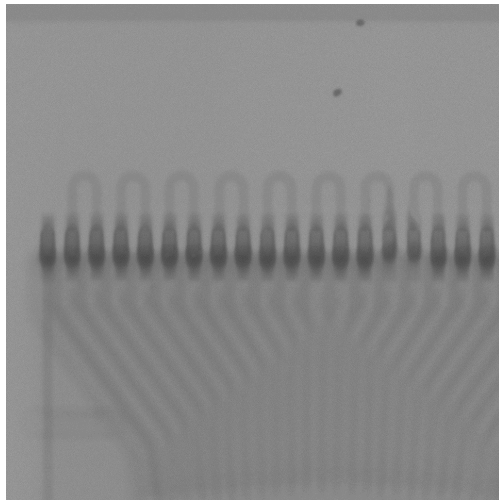
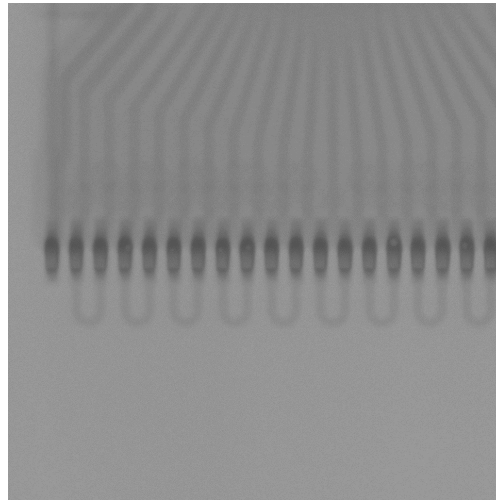


X-ray Images of SnAgCu vs SnPb

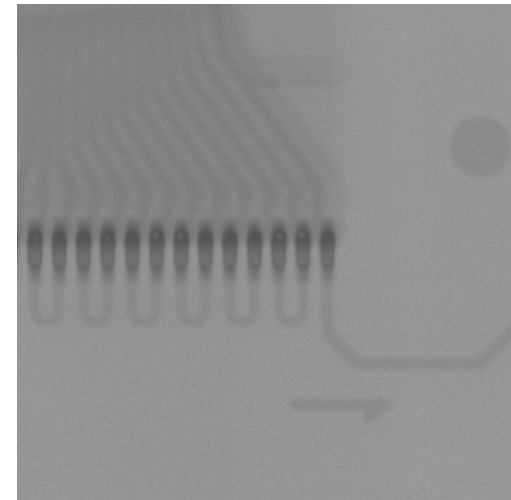


TSSOP48

Tin/Silver/Copper Joint



Tin/Lead Joint



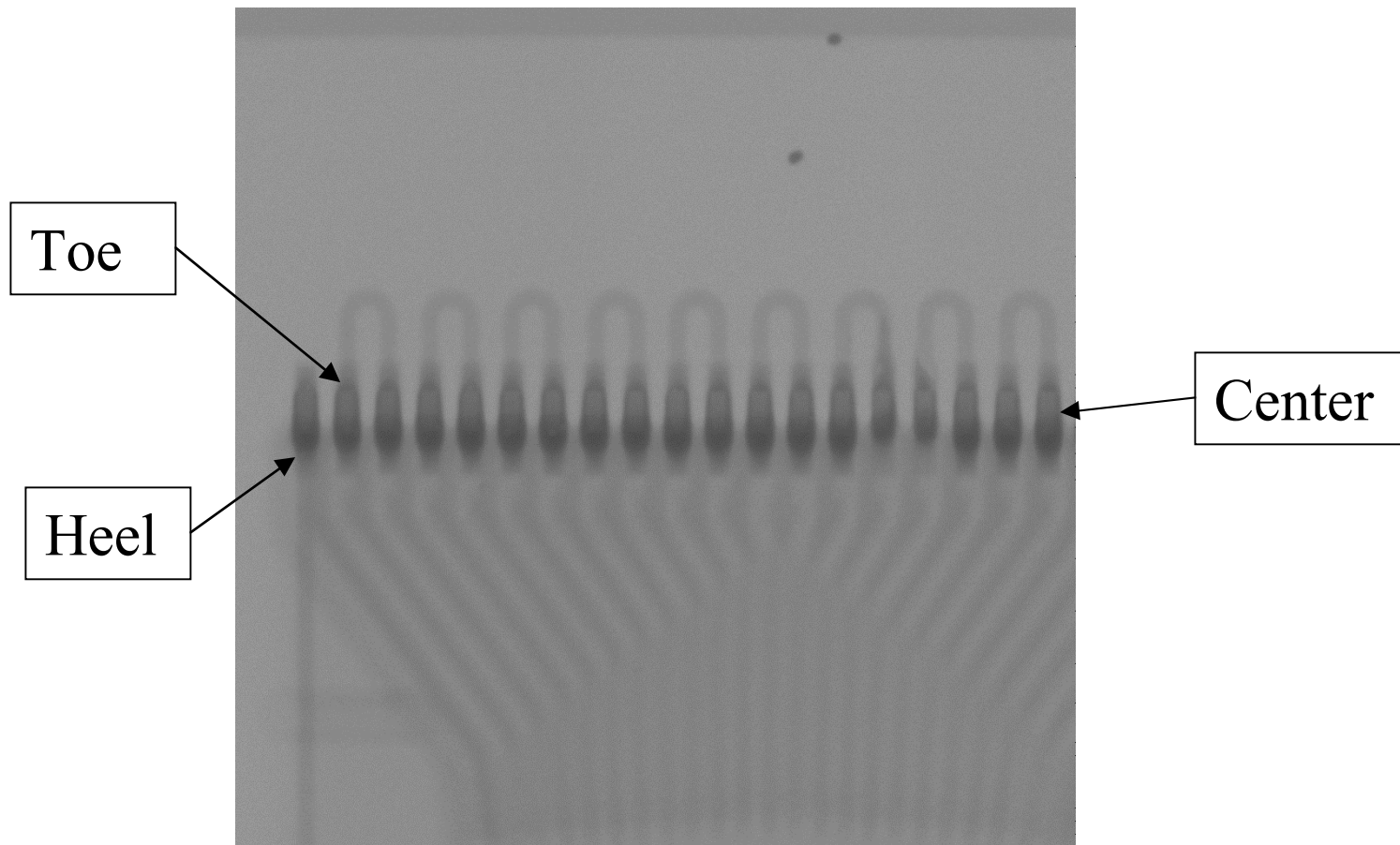
Tin/Silver/Copper paste

Tin/Lead coated Lead

Images are taken at 400 Field of View
(400 mils x 400 mils)

TSSOP48

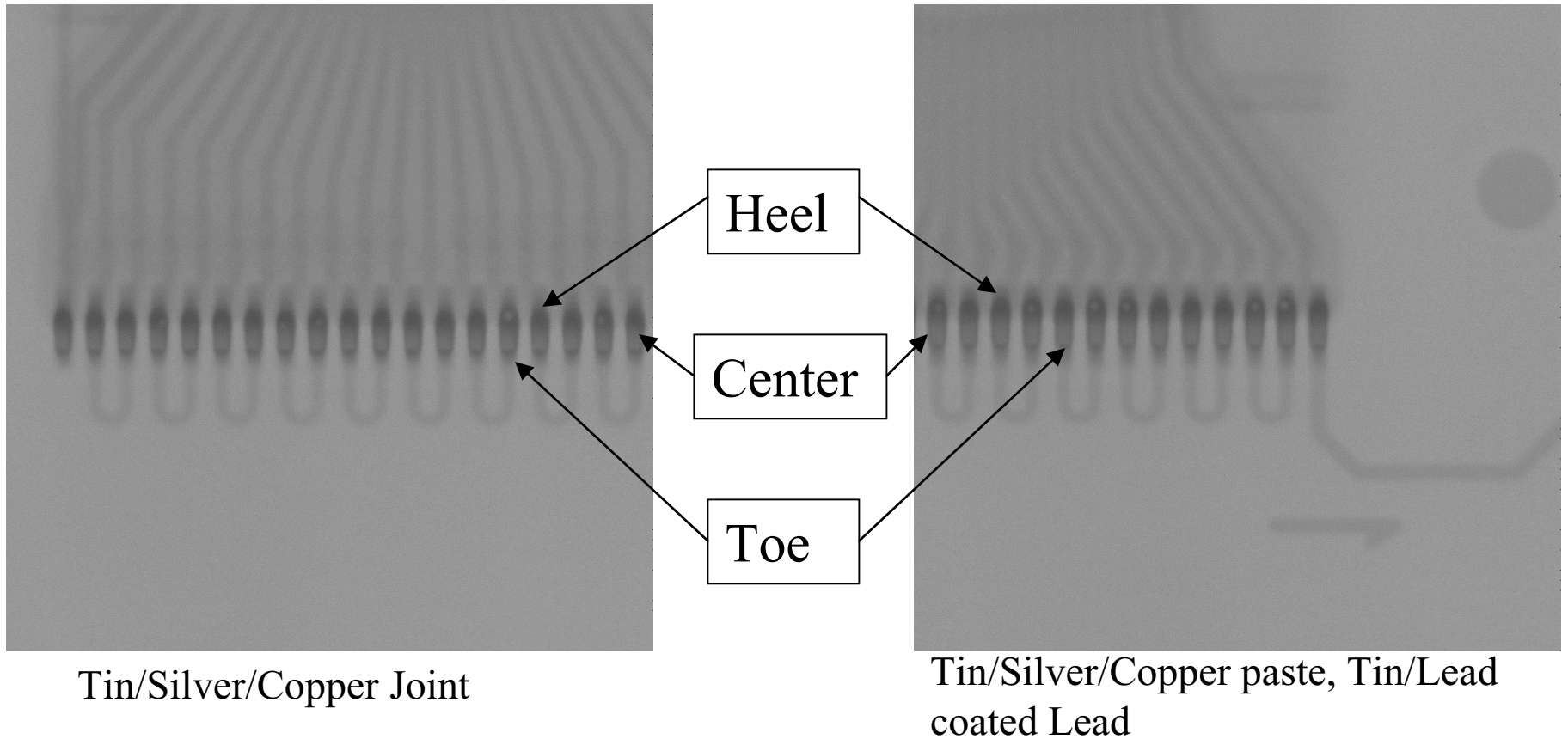
Tin/Lead Joint



Images are taken at 400 Field of View
(400 mils x 400 mils)

TSSOP48

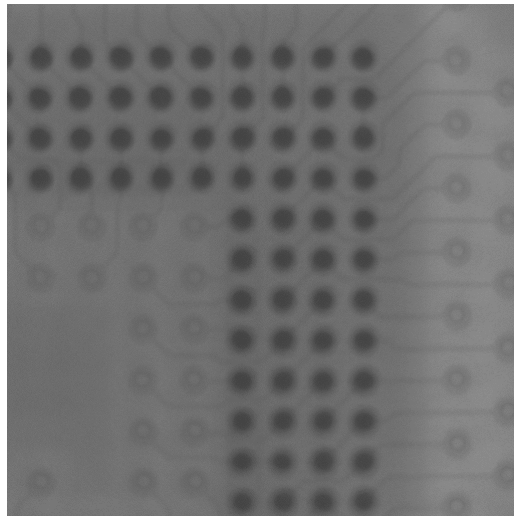
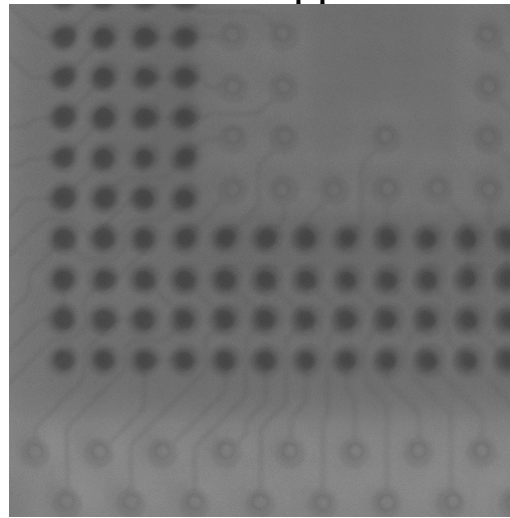
Lead Free Solder



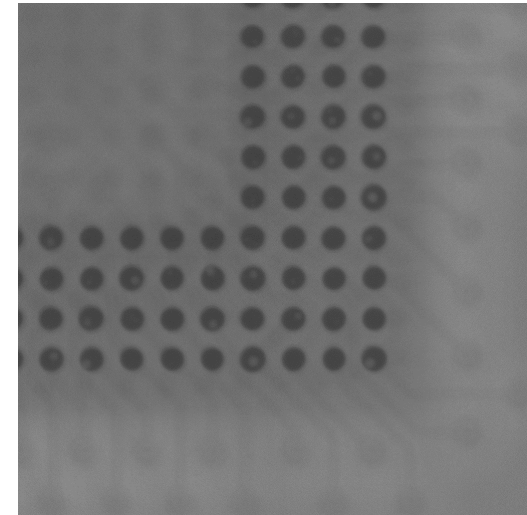
Images are taken at 400 Field of View
(400 mils x 400 mils)

CSP208

Tin/Silver/Copper Joint



Tin/Lead Joint



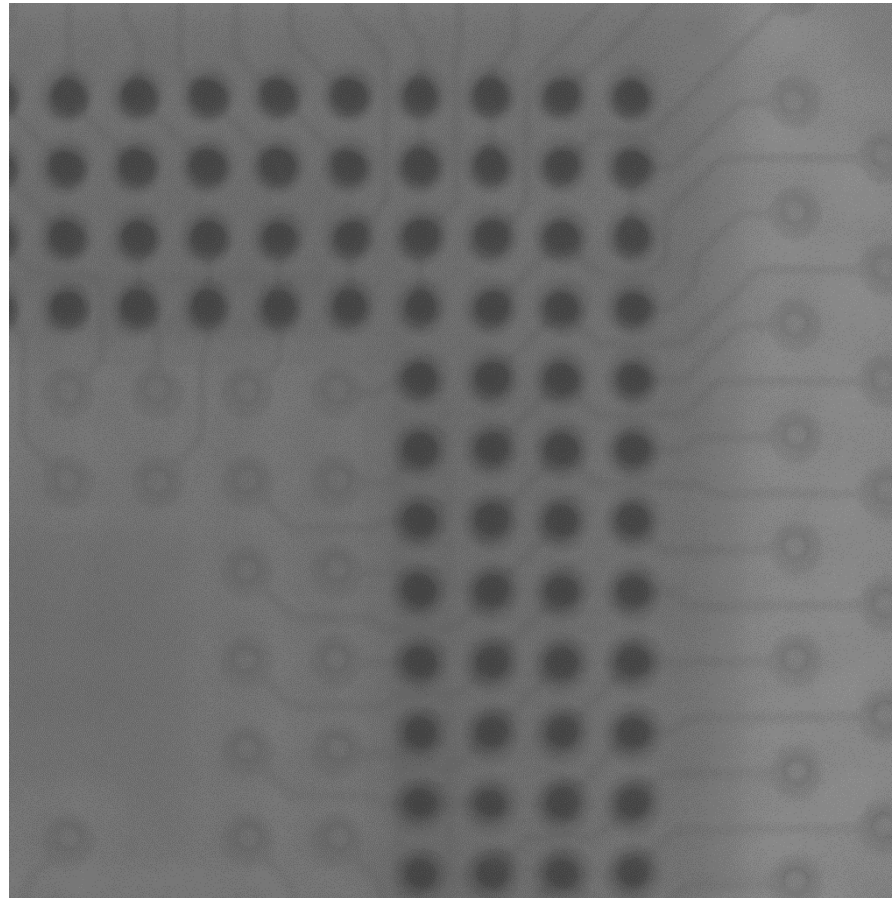
Tin/Silver/Copper paste

Tin/Lead coated Lead

Images are taken at 400 Field of View
(400 mils x 400 mils)

CSP208

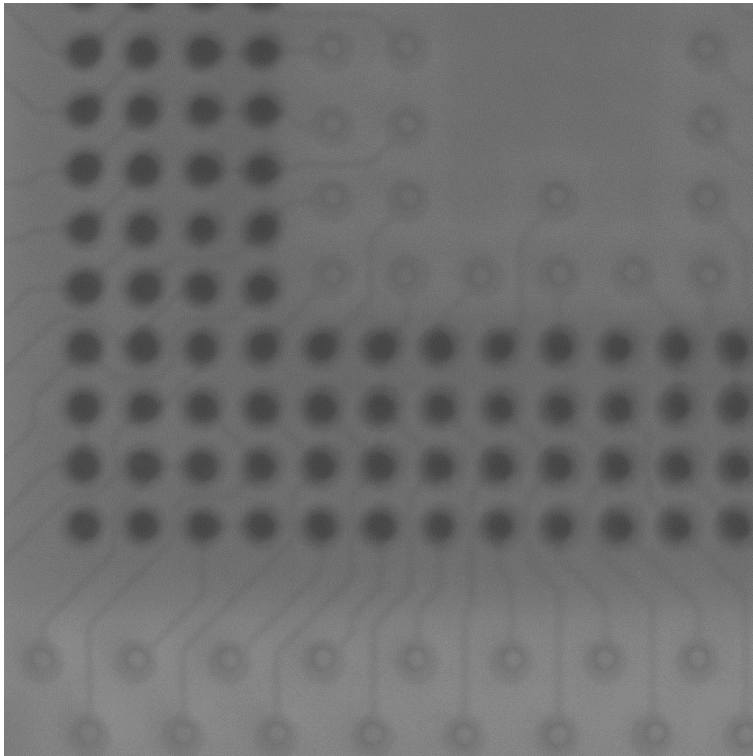
Tin/Lead



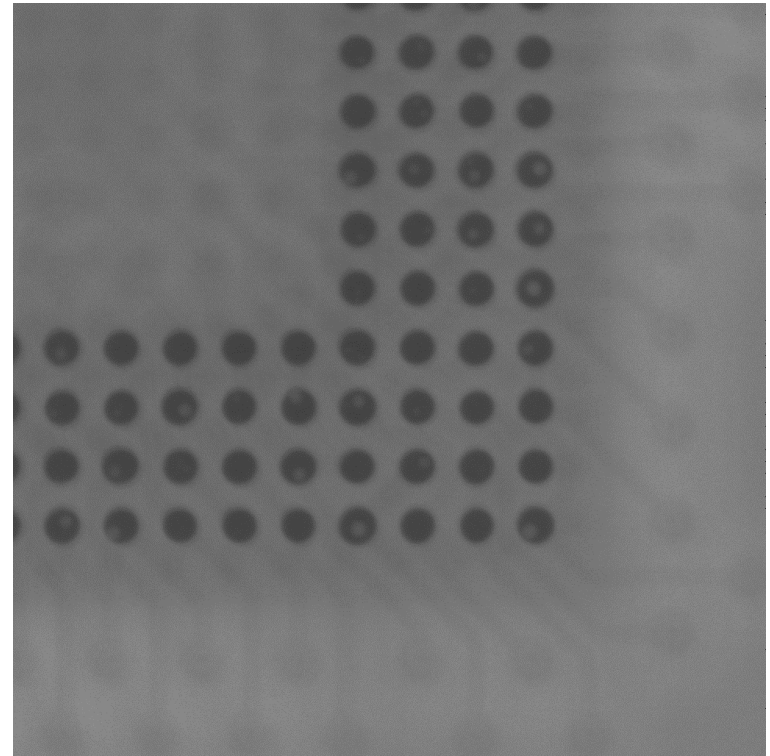
Images are taken at 400 Field of View
(400 mils x 400 mils)

CSP208

Lead Free Solder



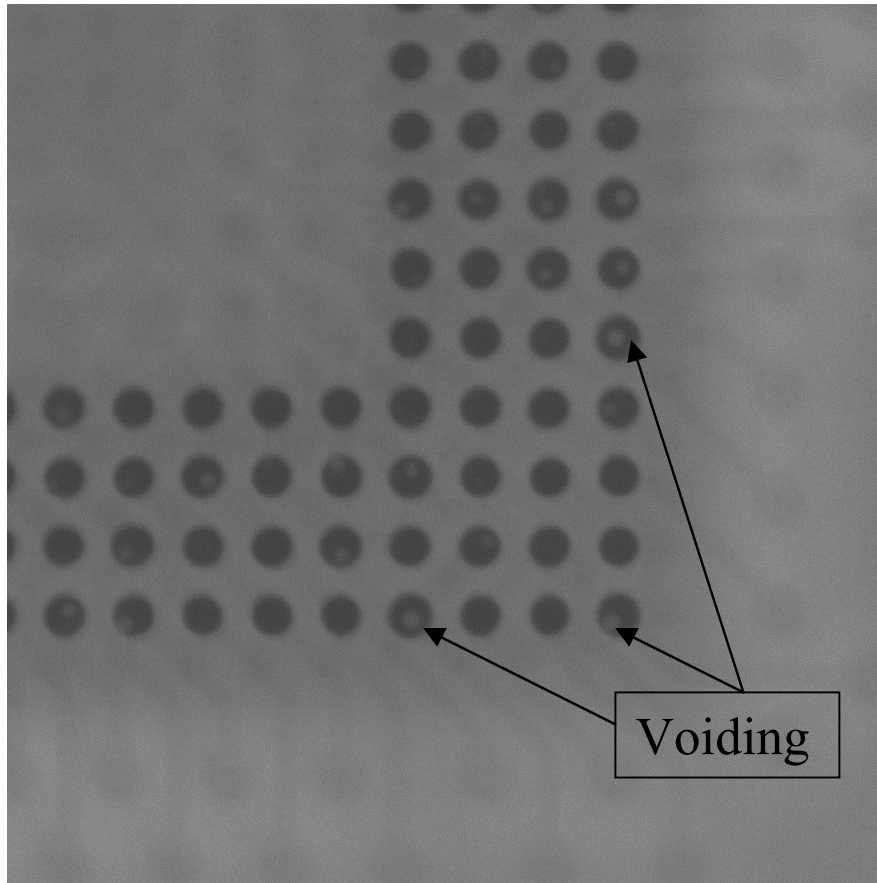
Tin/Silver/Copper Joint



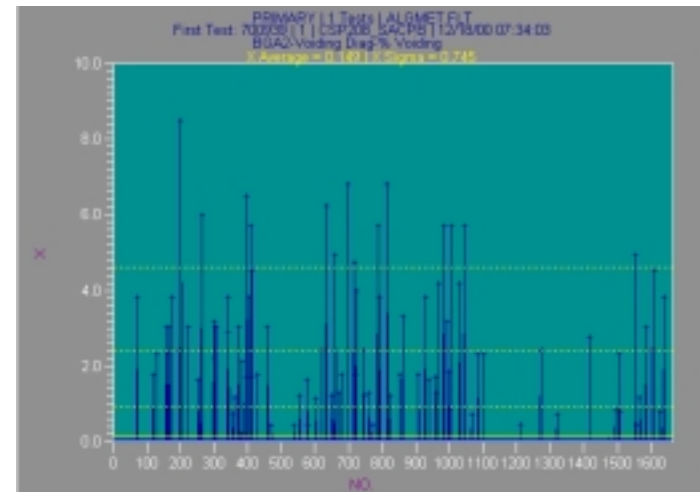
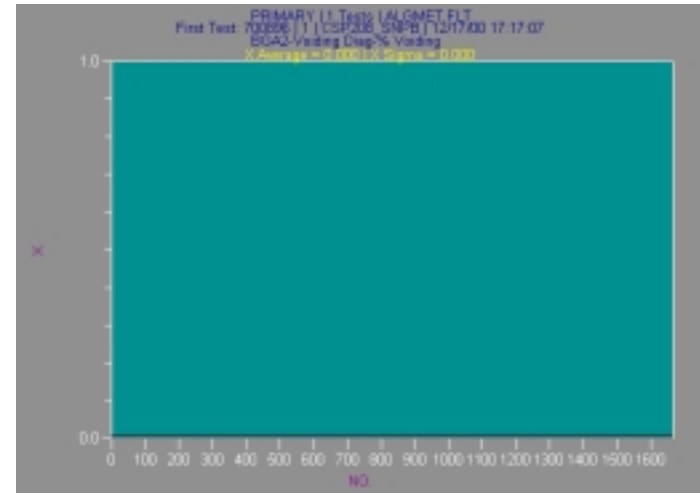
Tin/Silver/Copper paste, Tin/Lead coated Lead

Images are taken at 400 Field of View
(400 mils x 400 mils)

Increase in Voiding?



Tin/Silver/Copper paste, Tin/Lead coated Lead



Voiding Percentages as calculated by the Agilent 5DX